

Form PTO-1449

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

OCT 22 2003

Drawing Number (Optional)

TSMC-02-360

Application Number

10/618,536

Applicant

Jenn-Chen Lin et al.

Filing Date

07/11/03

Drawn At Unit

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
TT	6406996	6/18/02	Bernard et al.	438	653	9/30/00
TT	6169028	1/2/01	Wang et al.	438	653	1/26/99
TT	6309970	10/30/01	Ito et al.	438	687	8/30/99
TT	6274499	8/14/01	Gupta et al.	438	692	11/19/99
TT	6054769	4/25/00	Jeng	257	758	1/17/97
TT	6348407	2/19/02	Gupta et al.	438	637	3/15/01
TT	6365502	4/2/02	Paranjpe et al.	438	622	3/3/00

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portmanteau Pages, Etc.)

TT	TSMC-01-1676, Serial No. 10/361,732, filed on 02/10/03, assigned to common assignee, "Barrier Free Copper Interconnect by Multi-Layer Copper Seed".
TT	TSMC-02-338, Serial No. 10/350,837, filed on 01/24/03, assigned to common assignee, "Improved Method of Barrier-less Integration with Copper Alloy".
EXAMINER	DATE CONSIDERED
Thien Mue	12/26/2004

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.